

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.66665	100.0	10.18
			Subtotal	0.66665	100	10.18
Wire	Pure metal	Aluminium (Al)	7429-90-5	1.12484	100.0	17.1767
			Subtotal	1.12484	100	17.1767
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.04113	10.0	0.628
	Silver alloy	Silver (Ag)	7440-22-4	0.00823	2.0	0.1256
	Lead alloy	Lead (Pb)	7439-92-1	0.3619	88.0	5.5264
			Subtotal	0.41126	100	6.28
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00962	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00641	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00962	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03528	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.01366	99.81	488.8594
			Subtotal	32.07459	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.33837	100.0	5.167
			Subtotal	0.33837	100	5.167
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.23074	8.0	79.8752
	Filler	Silica fused	60676-86-0	52.96127	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.45769	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19615	0.3	2.99532
	Polymer	Epoxy resin system		6.53843	10.0	99.844
			Subtotal	65.38428	100	998.44
			Total	99.99999	100	1527.03371

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